

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

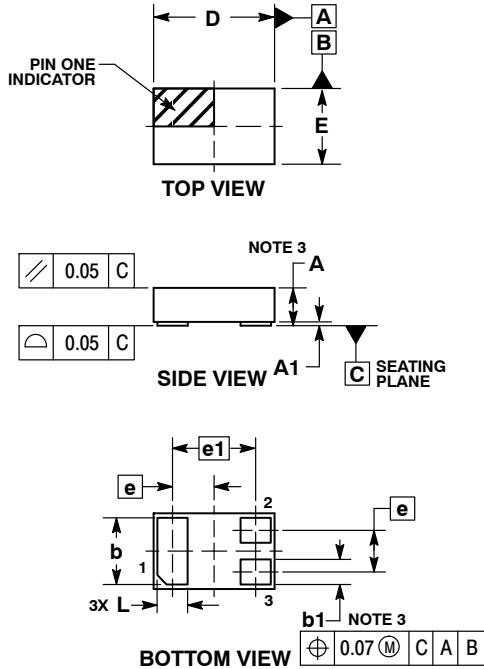
ON Semiconductor®



SCALE 4:1

UDFN3 1.6x1.0, 0.55P
CASE 517DY
ISSUE O

DATE 17 OCT 2017



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. POSITIONAL TOLERANCE APPLIES TO ALL THREE PADS.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.45	0.50	0.55
A1	---	---	0.05
b	0.83	0.88	0.93
b1	0.28	0.33	0.38
D	1.52	1.60	1.68
E	0.92	1.00	1.08
e	0.55 BSC		
e1	1.10 BSC		
L	0.35	0.40	0.45

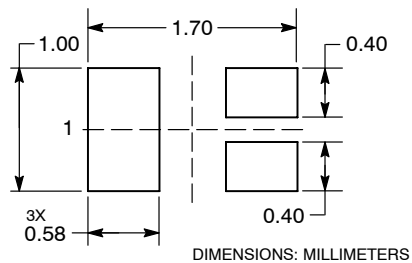
GENERIC MARKING DIAGRAM*



XX = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present. Some products may not follow the Generic Marking.

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	UDFN3 1.6X1.0, 0.55P	PAGE 1 OF 1

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